OPS Module

OPS-i730

◣ INTRODUCTION

OPS is designed to simplify the deployment and maintenance of IFP by allowing for easy installation and upgrades of computing modules without the need for complex cabling or external devices. The OPS module, which is a small form-factor computer, can be inserted into a slot on the back of an OPS-compatible IFP, effectively turning it into a powerful interactive computing platform.


◣ FEATURES

- The board-mounted 4G D4 has a 128-bit independent display, which is the only one in the industry that can achieve a thickness of 30MM.
- Anti-fouling, dust-proof, fully enclosed body, preventing dust from affecting product life
- Low CPU temperature and strong performance (Turbo on)
- TPY-C interface
- Strong anti-static (static cloth and cotton to prevent short circuit of OPS caused by static electricity)
- Normal operation at minus 15°-75°
- Maximum support for 6 3.0USB
- 8-layer PCB board with strong performance and double-layer design
- On-board WiFi, 2-in-1 audio
- Support: 4th-9th generation CPU/dual memory-up to 64G/5GWiFi Bluetooth/2.4G dual-band
- 30-42 Chassis Thickness/Japan Imported JAE Plug 4K 60HZ

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⬉ FEATURES IN DETAIL

All Aluminum Material

- All-aluminum integrated heat dissipation, wide groove design on the body surface for better heat dissipation, including double copper tubes and double radiators
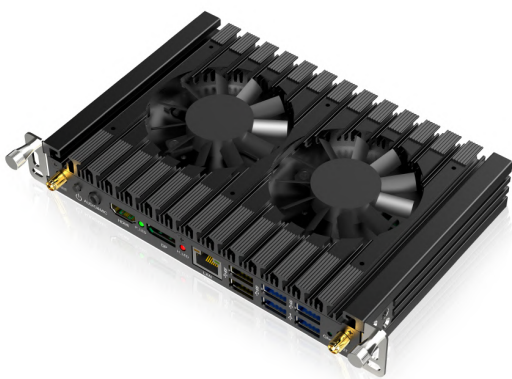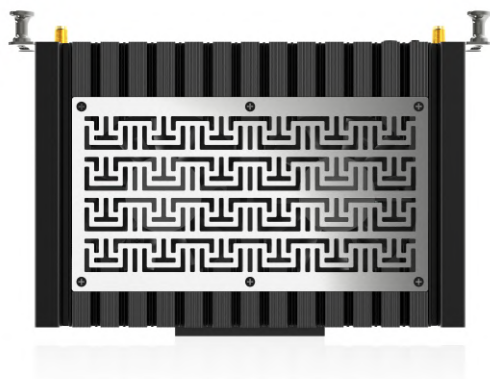
Double Cooling Fan

- Double cooling fan to dissipate the heat generated by electronic components and maintain an optimal operating temperature.

Ultra Light

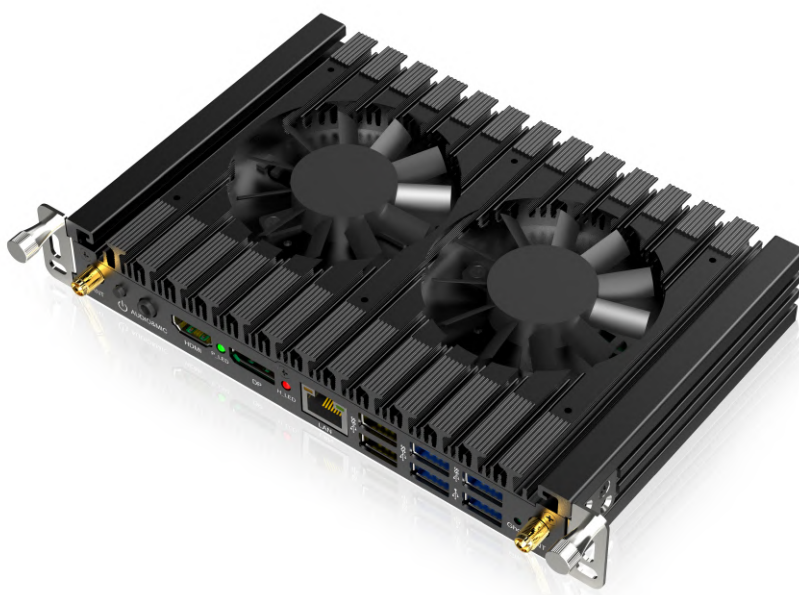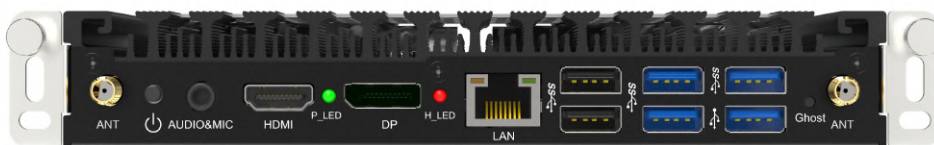- At the same time of high performance, the lightweight module design makes the installation very convenient

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◥ SPECIFICATIONS

Product Name		IFP Module - OPS-i730
Processor	CPU Model	I7-10750H<Primary Frequency-2.6G><overclockable>6 Core 12 Threads
Memory	technology	1 x SODIMMs DDR4
	Memory	DDR4-8G;
Display	Front End Output	DP-Max.3840 x 2160@60Hz
		HDMI-Max.3840 x 2160@30Hz
	JAE End	HDMI-Max.3840 x 2160@60Hz
Processor Graphics Card	Model	CPU integrated graphics
Hard Disk	SSD	M.2 2230 Solid State Hard Disk Interface（256G）
WIFI	Interface	M.2 2230 PCIe
	Support	Standard 2.4G (optional 2.4+5g dual frequency)
I/0 Interface	JAE Connector	1(JAE TX25 80-PIN)
	LAN	1 x RJ45.Gigabit
	USB	3 x USB3.0 & 3 x USB2.0
	Type-c	USB3.0
	audio frequency	1 x AUDIO OUT + 1 x MIN IN
	Super IO	Main board reserved support RS232
		Intelligent regulation of fan speed
Extension Interface	Mini-PCLe(Built-in)	1 x M.2 2230(WIFI)
		1 x M.2 2280(SSD)
Power Requirements	input voltage	DC-IN 19V-5A Complete machine calculation with CPU power
Physical Characteristics	size	180x 195x 30MM
	Shell material	Aluminum
Dissipate Heat	Cooling mode	5V dual fan cooling
Environmental	working temperature	0 - 40°C
	relative humidity	10%^90°C(non-condensing)
Sdk	operating system	Windows10 , Windows 11

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\ Product Display Diagram

ANT   AUDIO&MIC   HDMI   P_LED   DP   H_LED   LAN   Ghost ANT

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